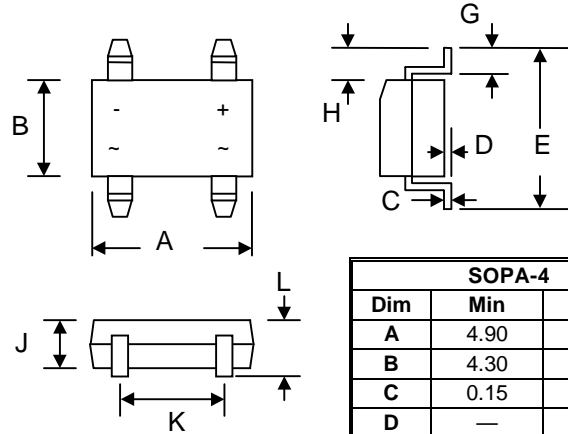


Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material – UL Flammability 94V-0



Mechanical Data

- Case: SOPA-4, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number
- **Lead Free: For RoHS / Lead Free Version**

SOPA-4		
Dim	Min	Max
A	4.90	5.10
B	4.30	4.60
C	0.15	0.25
D	—	0.15
E	6.00	6.40
G	0.30	0.70
H	0.90	1.10
J	—	1.50
K	3.90	4.10
L	1.22	1.42
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	D1UB	D1UB	D1UB	D1UB	D1UB	D1UB	D1UB	Unit
		A05	A10	A20	A60	A60	A80	A100	
Device marking code		UA05	UA10	UA20	UA40	UA60	UA80	UA100	
Peak Repetitive Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V_{RWM}								
DC Blocking Voltage	V_R								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) @ $T_A = 40^\circ\text{C}$	I_O	0.8							A
Average Rectified Output Current (Note 2) @ $T_A = 40^\circ\text{C}$									
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
I^2t Rating for Fusing ($t < 8.3\text{ms}$)	I^2t	5.0							A^2s
Forward Voltage per element @ $I_F = 0.4\text{A}$	V_{FM}	1.0							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$	I_{RM}	5.0							μA
At Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$		150							
Typical Junction Capacitance per leg (Note 3)	C_j	13							pF
Typical Thermal Resistance per leg (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	62.5 20							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150							$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3mm^2 solder pad.
2. Mounted on aluminum substrate PC board with 1.3mm^2 solder pad.
3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.